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HMC264LM3* Product Page Quick Links

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Comparable Parts

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Evaluation Kits

- HMC264LM3 Evaluation Board.

Documentation

Application Notes

- Mixer Application Note

Data Sheet

- HMC264LM3 Data Sheet

Tools and Simulations

- HMC264LM3 S-Parameters

Reference Materials

Quality Documentation

- Semiconductor Qualification Test Report: PHEMT-A (QTR: 2013-00267)

Design Resources

- HMC264LM3 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

Discussions

View all HMC264LM3 EngineerZone Discussions

Sample and Buy

Visit the product page to see pricing options

Technical Support

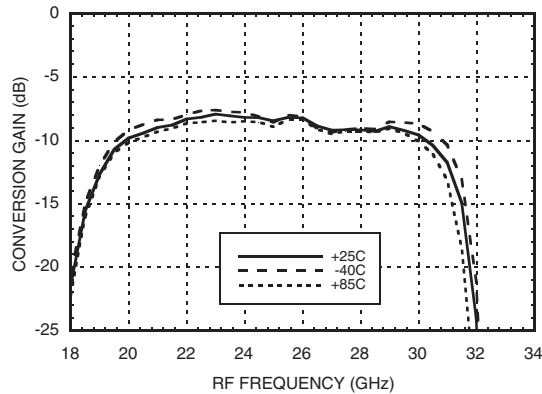
Submit a technical question or find your regional support number

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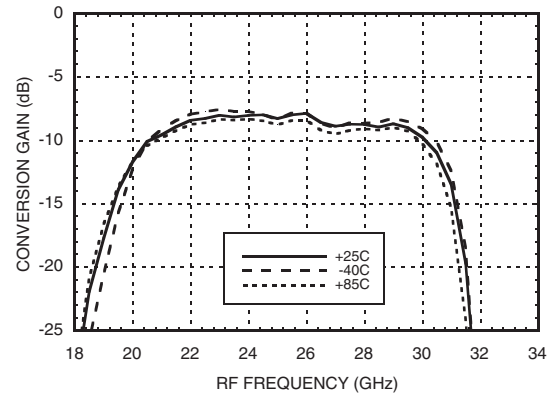
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GaAs MMIC SUB-HARMONIC SMT MIXER, 20 - 30 GHz

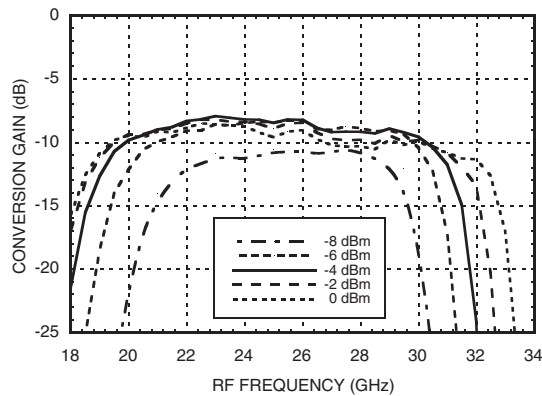
**Conversion Gain vs.
Temperature @ LO = -4 dBm, Vdd = +4V**



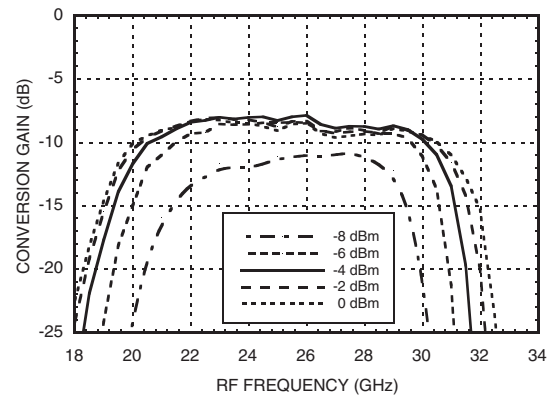
**Conversion Gain vs.
Temperature @ LO = -4 dBm, Vdd = +3V**



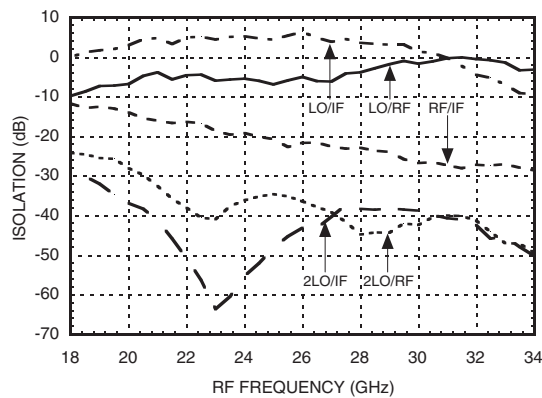
**Conversion Gain
vs. LO Drive @ Vdd = +4V**



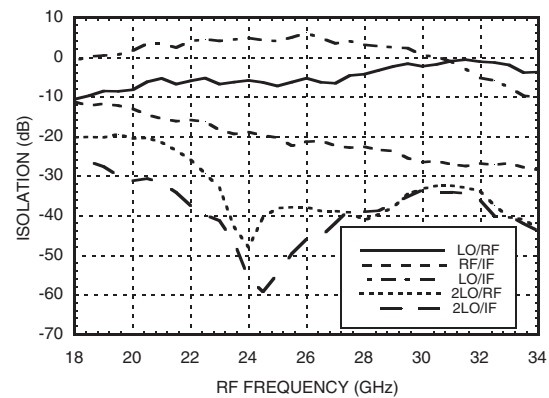
**Conversion Gain
vs. LO Drive @ Vdd = +3V**



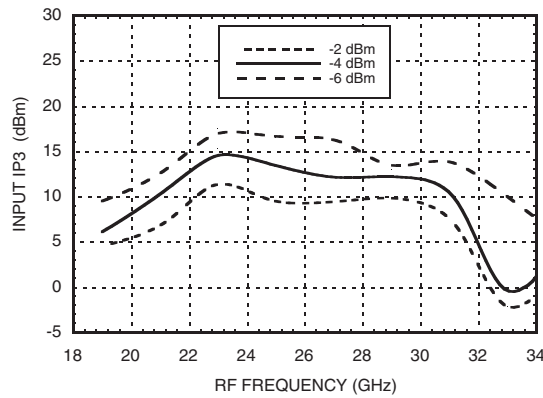
Isolation @ LO = -4 dBm, Vdd = +4V



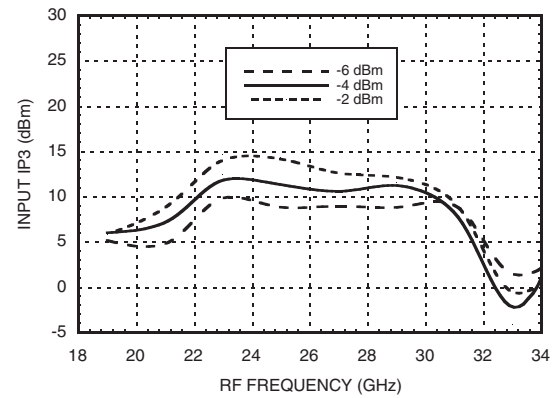
Isolation @ LO = -4 dBm, Vdd = +3V



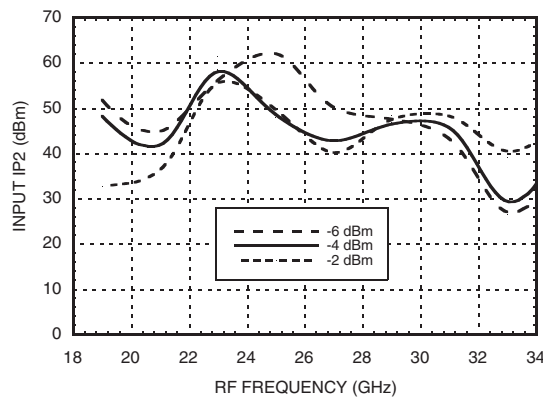
Input IP3 vs. LO Drive @ Vdd = +4V *



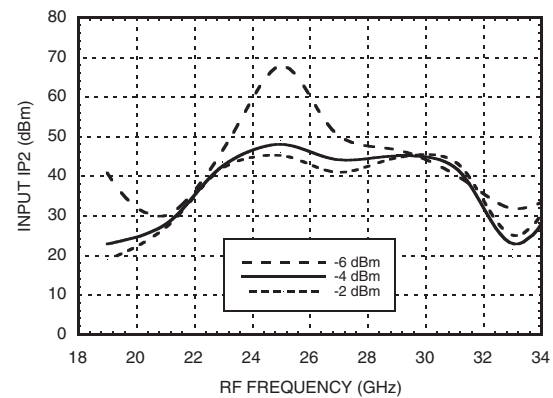
Input IP3 vs. LO Drive @ Vdd = +3V *



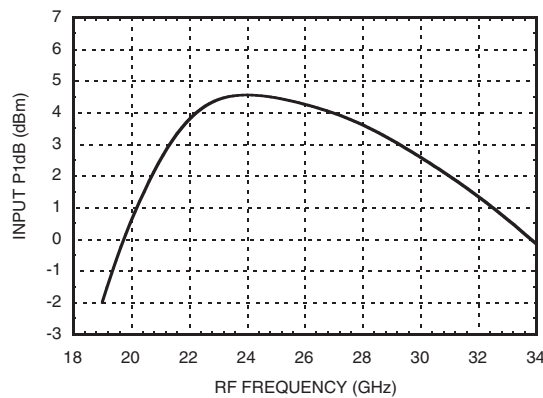
Input IP2 vs. LO Drive @ Vdd = +4V *



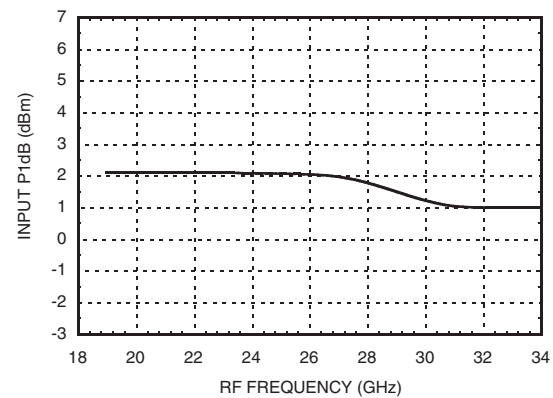
Input IP2 vs. LO Drive @ Vdd = +3V *



Input P1dB @ LO = -4 dBm, Vdd = +4V



Input P1dB @ LO = -4 dBm, Vdd = +3V

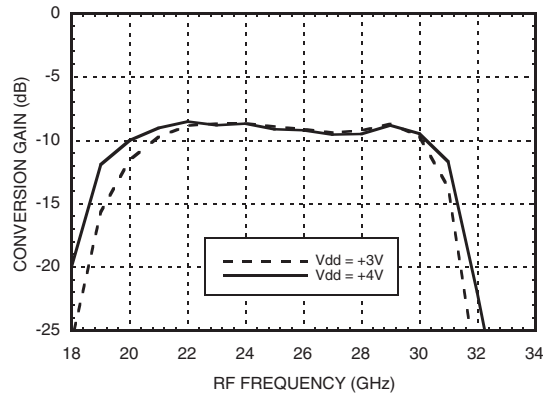


* Two-tone input power = -10 dBm each tone, 1 MHz spacing.

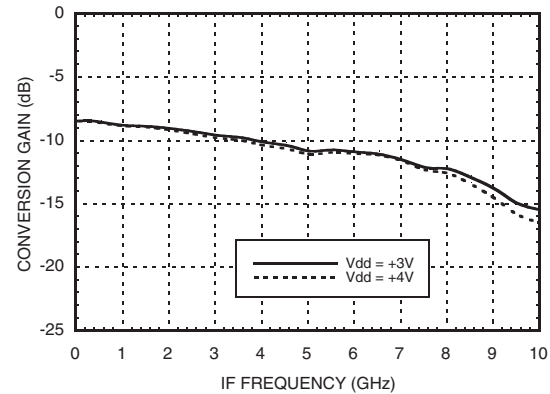
For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
Order On-line at www.hittite.com

Upconverter Performance

Conversion Gain, LO = -4 dBm Vdd = +4V

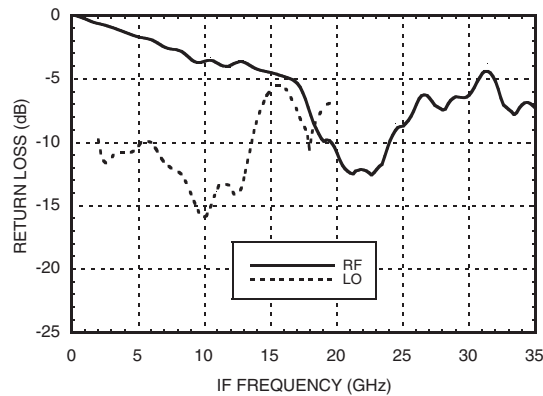


IF Bandwidth @ LO = -4 dBm



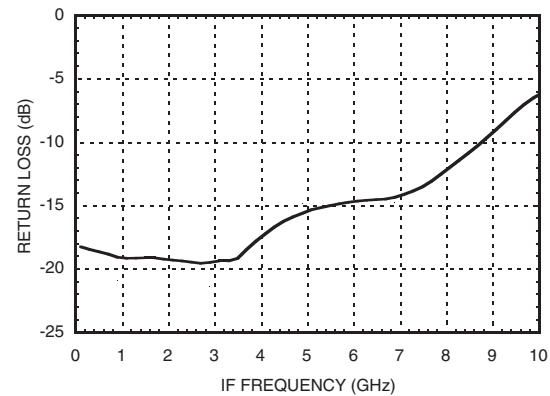
RF & LO Return Loss

@ LO = -4 dBm, Vdd = +4V



IF Return Loss

@ LO = -4 dBm, Vdd = +4V



MxN Spurious Outputs

@ LO = -4 dBm, Vdd = +4V

	nLO					
mRF	±5	±4	±3	±2	±1	0
-3						
-2	34.8					
-1	61.8	26.1	32.6			
0				14.1	-26.9	
1				X	33.8	12.3
2		49.0	48.1			
3	78.8	81.3				

RF = 30 GHz @ -10 dBm
LO = 13.5 GHz @ -4 dBm
All values in dBc below IF power level.

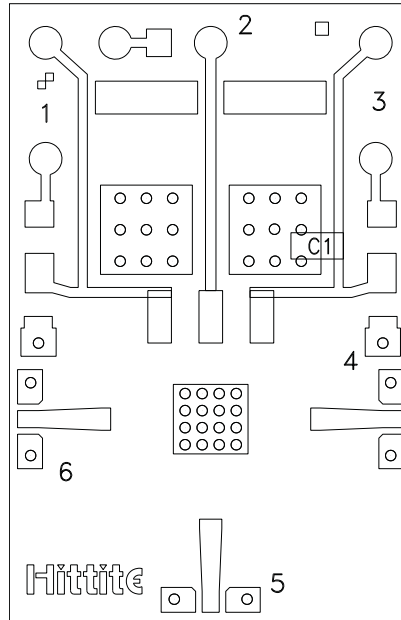
Absolute Maximum Ratings

RF / IF Input (Vdd = +5V)	+13 dBm
LO Drive (Vdd = +5V)	+13 dBm
Vdd	5.5V
Continuous P _{diss} (Ta = 85 °C) (derate 2.52 mW/°C above 85 °C)	227 mW
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

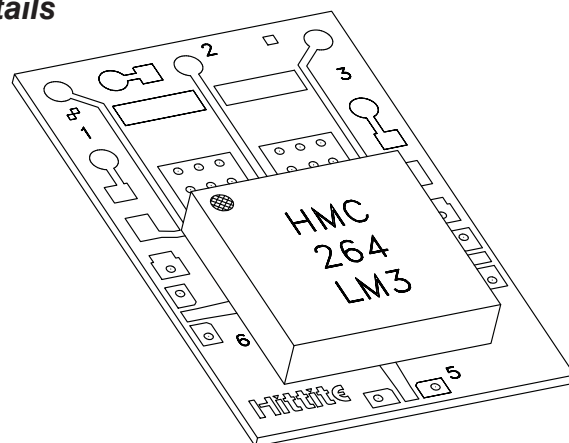
Evaluation PCB



The grounded Co-Planar Wave Guide (CPWG) PCB input/output transitions allow use of Ground-Signal-Ground (GSG) probes for testing. Suggested probe pitch is 400mm (16 mils). Alternatively, the board can be mounted in a metal housing with 2.4 mm coaxial connectors.

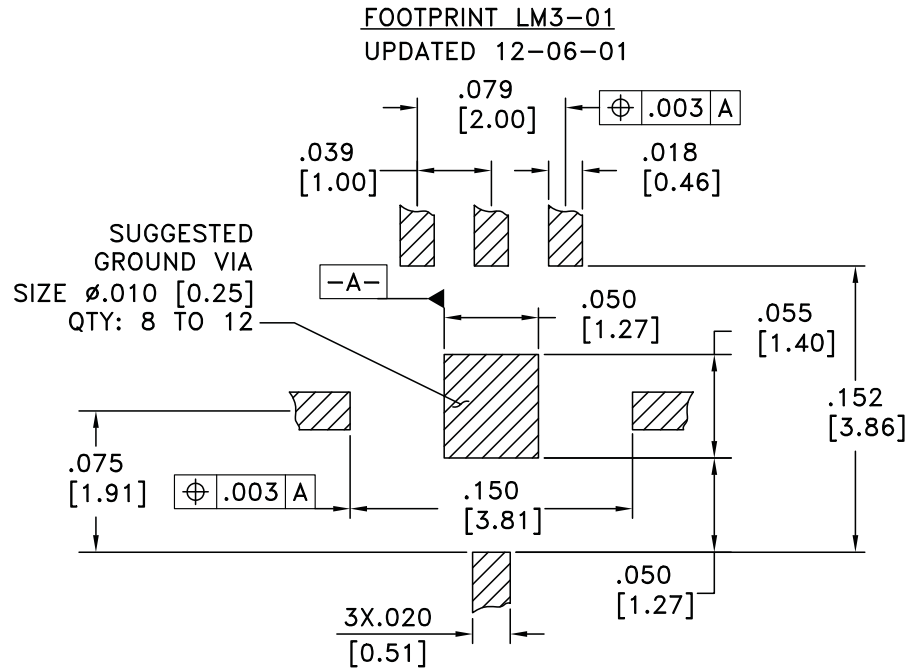
Evaluation Circuit Board Layout Design Details

Layout Technique	Micro Strip to CPWG
Material	Rogers 4003 with 1/2 oz. Cu
Dielectric Thickness	0.008" (0.20 mm)
Microstrip Line Width	0.018" (0.46 mm)
CPWG Line Width	0.016" (0.41 mm)
CPWG Line to GND Gap	0.005" (0.13 mm)
Ground to Via Hole Diameter	0.008" (0.20 mm)
C1	100 pF Capacitor, 0402 Pkg.



LM3 package mounted to evaluation PCB

Suggested LM3-01 PCB Land Pattern Tolerance: $\pm 0.003"$ (± 0.08 mm)



HMC264LM3 Recommended SMT Attachment Technique

Preparation & Handling of the LM3 Millimeterwave Package for Surface Mounting

The HMC LM3 package was designed to be compatible with high volume surface mount PCB assembly processes. The LM3 package requires a specific mounting pattern to allow proper mechanical attachment and to optimize electrical performance at millimeterwave frequencies. This PCB layout pattern can be found on each LM3 product data sheet. It can also be provided as an electronic drawing upon request from Hittite Sales & Application Engineering.

Follow these precautions to avoid permanent damage:

Cleanliness: Observe proper handling procedures to ensure clean devices and PCBs. LM3 devices should remain in their original packaging until component placement to ensure no contamination or damage to RF, DC & ground contact areas.

Static Sensitivity: Follow ESD precautions to protect against ESD strikes.

General Handling: Handle the LM3 package on the top with a vacuum collet or along the edges with a sharp pair of bent tweezers. Avoiding damaging the RF, DC, & ground contacts on the package bottom. Do not apply excess pressure to the top of the lid.

Solder Materials & Temperature Profile: Follow the information contained in the application note. Hand soldering is not recommended. Conductive epoxy attachment is not recommended.

Solder Paste

Solder paste should be selected based on the user's experience and be compatible with the metallization systems used. See the LM3 data sheet Outline drawing for pin & ground contact metallization schemes.

Solder Paste Application

Solder paste is generally applied to the PCB using either a stencil printer or dot placement. The volume of solder paste will be dependent on PCB and component layout and should be controlled to ensure consistent mechanical & electrical performance. Excess solder may create unwanted electrical parasitics at high frequencies.

Solder Reflow

The soldering process is usually accomplished in a reflow oven but may also use a vapor phase process. A solder reflow profile is suggested above.

Prior to reflowing product, temperature profiles should be measured using the same mass as the actual assemblies. The thermocouple should be moved to various positions on the board to account for edge and corner effects and varying component masses. The final profile should be determined by mounting the thermocouple to the PCB at the location of the device.

Follow solder paste and oven vendor's recommendations when developing a solder reflow profile. A standard profile will have a steady ramp up from room temperature to the pre-heat temperature to avoid damage due to thermal shock. Allow enough time between reaching pre-heat temperature and reflow for the solvent in the paste to evaporate and the flux to completely activate. Reflow must then occur prior to the flux being completely driven off. The duration of peak reflow temperature should not exceed 15 seconds. Packages have been qualified to withstand a peak temperature of 235°C for 15 seconds. Verify that the profile will not expose device to temperatures in excess of 235°C.

Cleaning

A water-based flux wash may be used.

